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# H5N2003P

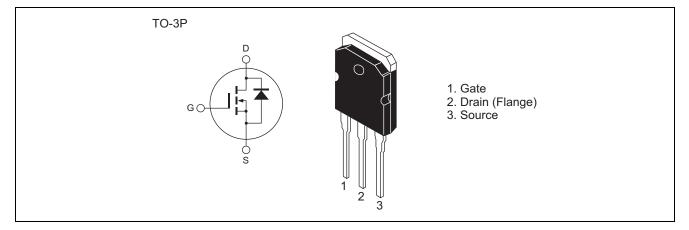
Silicon N Channel MOS FET High Speed Power Switching

> REJ03G0235-0100Z Rev.1.00 Apr.09.2004

### Features

- Low on-resistance
- Low leakage current
- High speed switching

### Outline



## **Absolute Maximum Ratings**

			(Ta = 25°C)
Item	Symbol	Ratings	Unit
Drain to Source voltage	V <sub>DSS</sub>	200	V
Gate to Source voltage	V <sub>GSS</sub>	±30	V
Drain current	I <sub>D</sub>	60	A
Drain peak current	Note1 D (pulse)	240	A
Body-Drain diode reverse Drain current	I <sub>DR</sub>	60	A
Body-Drain diode reverse Drain peak current	Note1 DR (pulse)	240	A
Avalanche current	I <sub>AP</sub> <sup>Note3</sup>	40	A
Channel dissipation	Pch <sup>Note2</sup>	150	W
Channel to case thermal impedance	θch-c	0.833	°C/W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1.  $PW \le 10 \ \mu s$ , duty cycle  $\le 1\%$ 

2. Value at Tc = 25°C

3. Tch  $\leq 150^{\circ}C$ 



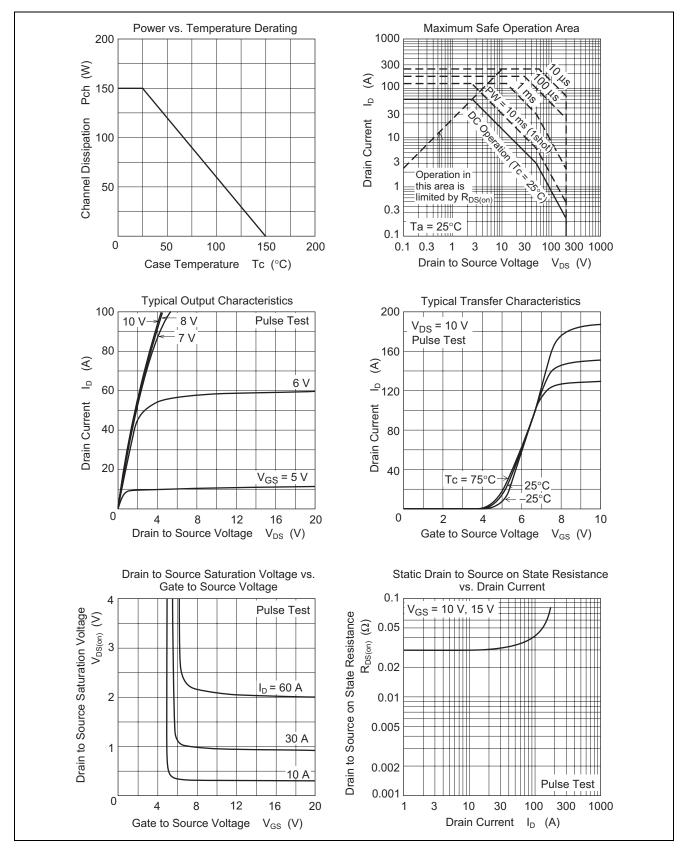
# **Electrical Characteristics**

						$(Ta = 25^{\circ}C)$
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to Source breakdown voltage	V <sub>(BR)DSS</sub>	200		_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Zero Gate voltage drain current	I <sub>DSS</sub>	_		1	μA	$V_{DS} = 200 V, V_{GS} = 0$
Gate to Source leak current	I <sub>GSS</sub>	_	_	±0.1	μΑ	$V_{GS}=\pm 30~V,~V_{DS}=0$
Gate to Source cutoff voltage	V <sub>GS(off)</sub>	3.0	_	4.0	V	$V_{DS}$ = 10 V, $I_{D}$ = 1 mA
Forward transfer admittance	yfs	26	44	—	S	$I_D = 30 \text{ A}, V_{DS} = 10 \text{ V}^{Note4}$
Static Drain to Source on state resistance	$R_{\text{DS(on)}}$	_	0.032	0.042	Ω	$I_D = 30 \text{ A}, V_{GS} = 10 \text{ V}^{Note4}$
Input capacitance	Ciss	_	5150	_	pF	V <sub>DS</sub> = 25 V
Output capacitance	Coss	_	660	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	110	_	pF	f = 1 MHz
Turn-on delay time	td(on)	—	65	—	ns	I <sub>D</sub> = 30 A
Rise time	tr	—	260	—	ns	V <sub>GS</sub> = 10 V
Turn-off delay time	td(off)	_	200	_	ns	$R_L = 3.33 \Omega$
Fall time	tf	_	180	_	ns	Rg = 10 Ω
Total Gate charge	Qg	_	132	_	nC	V <sub>DD</sub> = 160 V
Gate to Source charge	Qgs	_	30	_	nC	$V_{GS} = 10 V$ $I_{D} = 60 A$
Gate to Drain charge	Qgd	—	60	—	nC	
Body-Drain diode forward voltage	V <sub>DF</sub>		1.0	1.5	V	$I_F = 60 \text{ A}, V_{GS} = 0^{Note4}$
Body-Drain diode reverse recovery time	trr	—	190	—	ns	$I_F = 60 \text{ A}, V_{GS} = 0$ diF/dt = 100 A/µs
Body-Drain diode reverse recovery charge	Qrr	_	1.4	—	μC	

Notes: 4. Pulse test

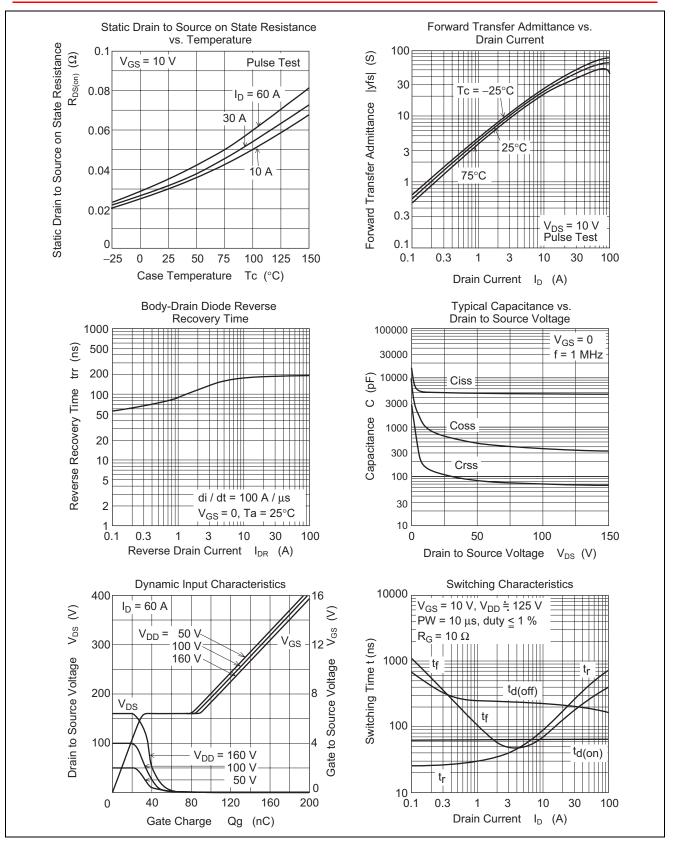


### **Main Characteristics**

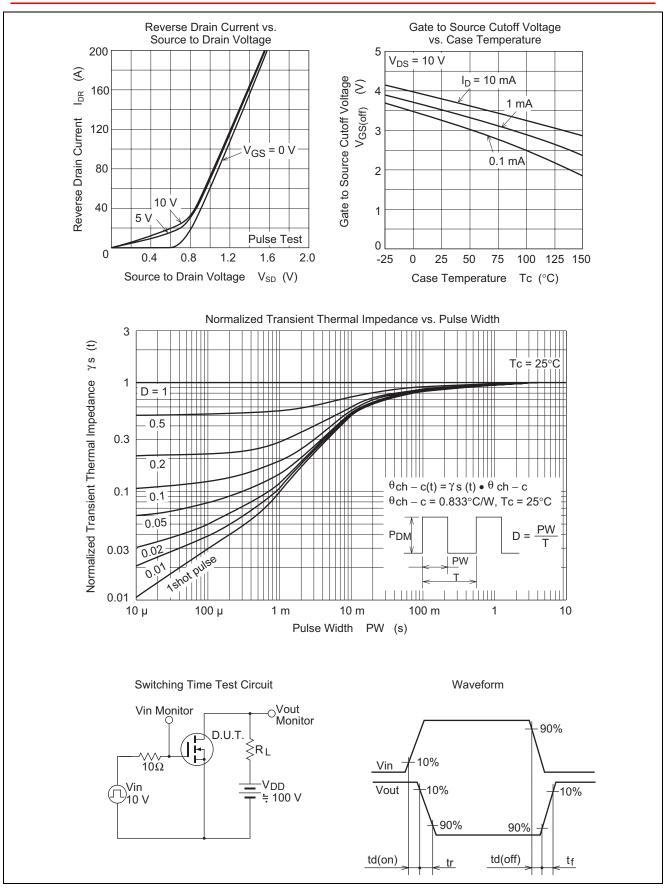


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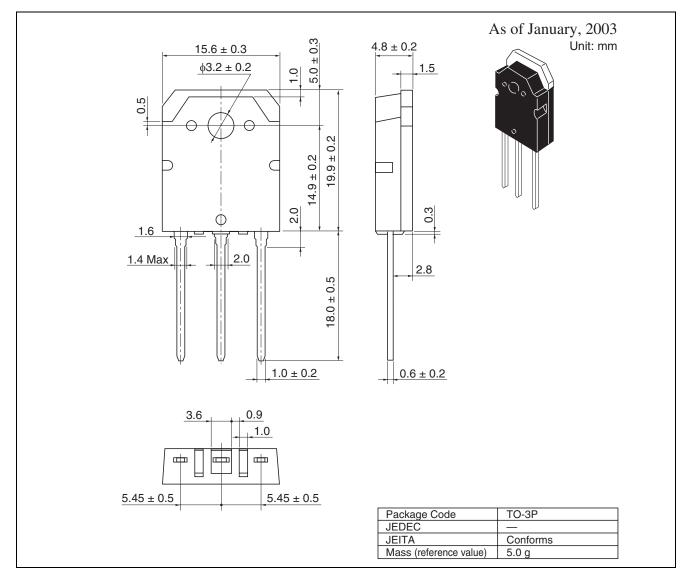


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## **Package Dimensions**



## **Ordering Information**

Part Name	Quantity	Shipping Container	
H5N2003P-E	30 pcs	Plastic magazine	

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.



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